



FOR IMMEDIATE RELEASE

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**AEHR TEST SYSTEMS RECEIVES MULTI-MILLION DOLLAR  
FOX™ WAFER-LEVEL BURN-IN ORDER**

**Fremont, CA (March 14, 2006)** – Aehr Test Systems (Nasdaq: AEHR), a leading supplier of semiconductor test and burn-in equipment, today announced it has received a multi-million dollar order for its FOX wafer-level burn-in system from a leading automotive IC manufacturer. The system is expected to ship in calendar year 2007.

“We are very excited about this order for wafer-level burn-in of automotive integrated circuits and believe it validates our leadership position in the full wafer contact burn-in and test market,” said Carl Buck, vice president of marketing of Aehr Test Systems. “This program could result in follow-on orders for multiple FOX wafer-level burn-in and test systems over the next few years. A key aspect of this system is to provide a cost-effective full wafer probe that can make contact to thousands of fine-pitch pads simultaneously over the entire wafer and over the temperature range required for burn-in.”

“This strategic order is in a growing market area that could represent a significant revenue stream for our FOX systems,” said Rhea Posedel, chairman and chief executive officer of Aehr Test Systems. “We believe the industry’s need for wafer-level test and burn-in will continue to grow as the increasing demand for multi-chip packages for automotive and mobile electronics products drives the need for known-good-die.”

As usage of electronics in automobiles grows, high-density packaging holding multiple die becomes increasingly important. With multi-die packaging, each of the die in the package must be extraordinarily reliable, enabling the multi-die package to meet the stringent reliability demands of the automotive manufacturers. Aehr Test’s FOX systems provide full wafer contact parallel test and burn-in solutions for the die before they are assembled into the package. This enables the reliability screening to be done on the die before the assembly of the multi-die package, avoiding the costly waste of scrapping entire multi-chip packages when only one of the die fails the reliability screen.

**About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a leading worldwide provider of systems for burning-in and testing DRAM and logic integrated circuits and has an installed base of more than 2,500 systems worldwide. Aehr Test has developed and introduced several innovative products, including the FOX, MTX and MAX systems and the DiePak® carrier. The FOX system is a full wafer contact test and burn-in system. The MTX system is a massively

parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX system can effectively burn-in and functionally test complex devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at [www.aehr.com](http://www.aehr.com).

**Safe Harbor Statement**

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding customer demand and acceptance of Aehr Test's products. Actual results may vary from projected results. These risks and uncertainties include, without limitation, acceptance by customers of the FOX technology, acceptance by customers of the FOX systems shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K and 10-Q reports and other reports from time to time filed with the Securities and Exchange Commission (SEC) for a more detailed description of the risks facing our business. The Company disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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